

U\_FPGA\_IO  
FPGA\_IO.SchDoc

U\_B2B\_Connector  
B2B\_Connector.SchDoc

U\_FPGA\_MGT  
FPGA\_MGT.SchDoc

U\_POWER  
POWER.SchDoc

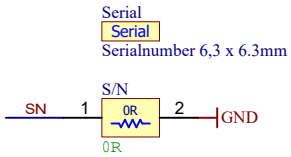
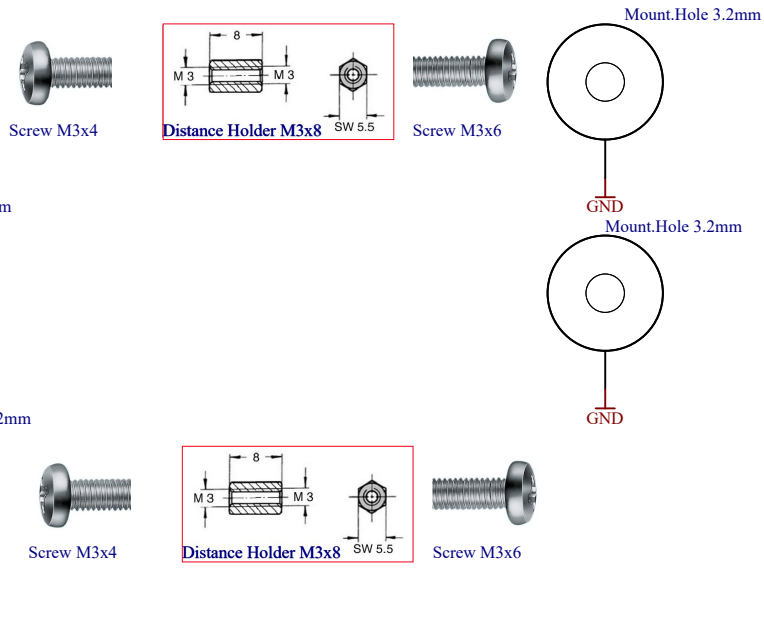
U\_FPGA\_MISC  
FPGA\_MISC.SchDoc

U\_Revision  
Revision\_Changes.SchDoc

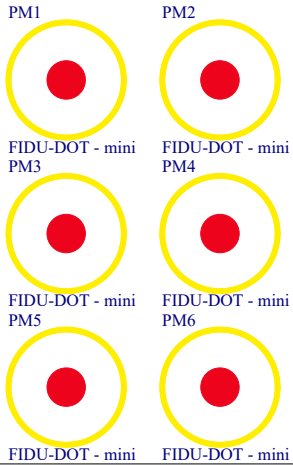
Special notes:

- 
- 

Top of Board

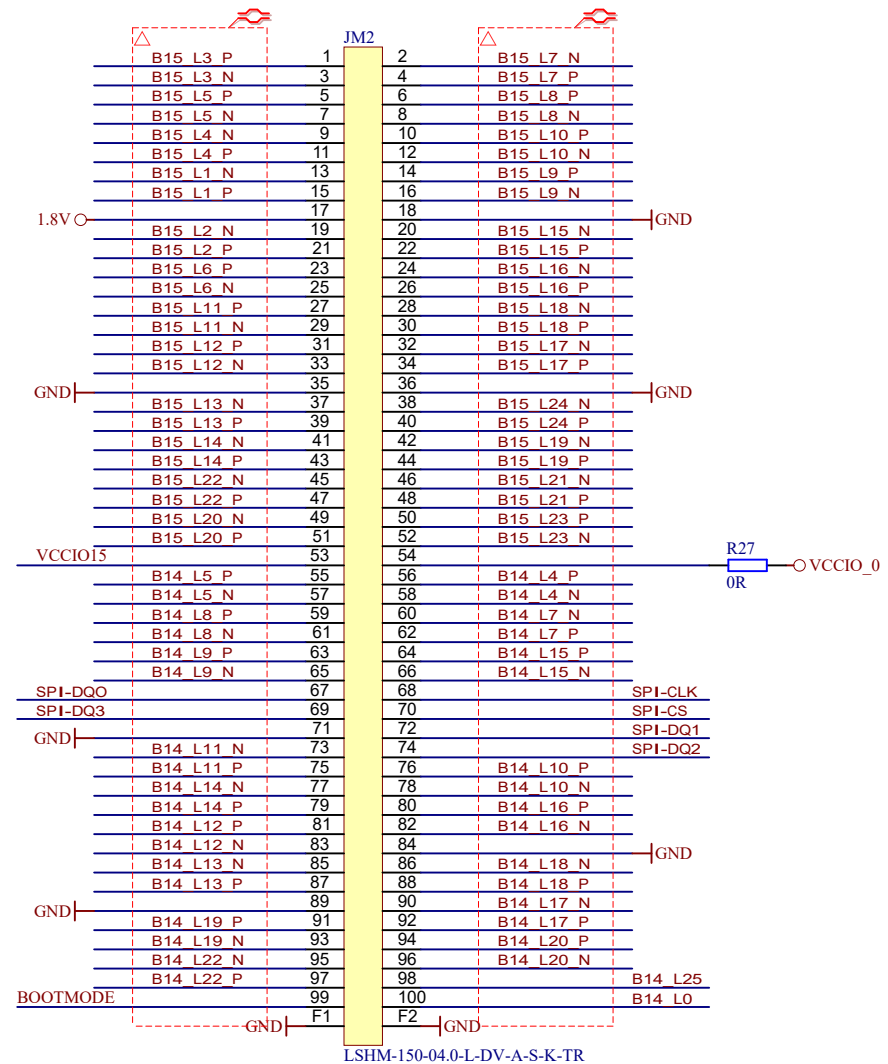
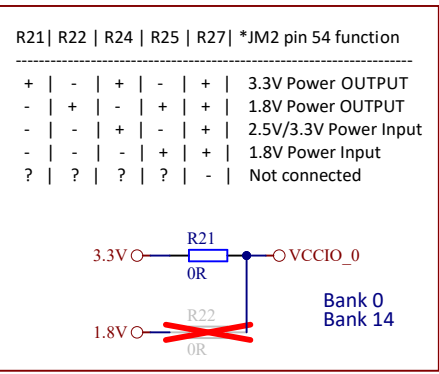
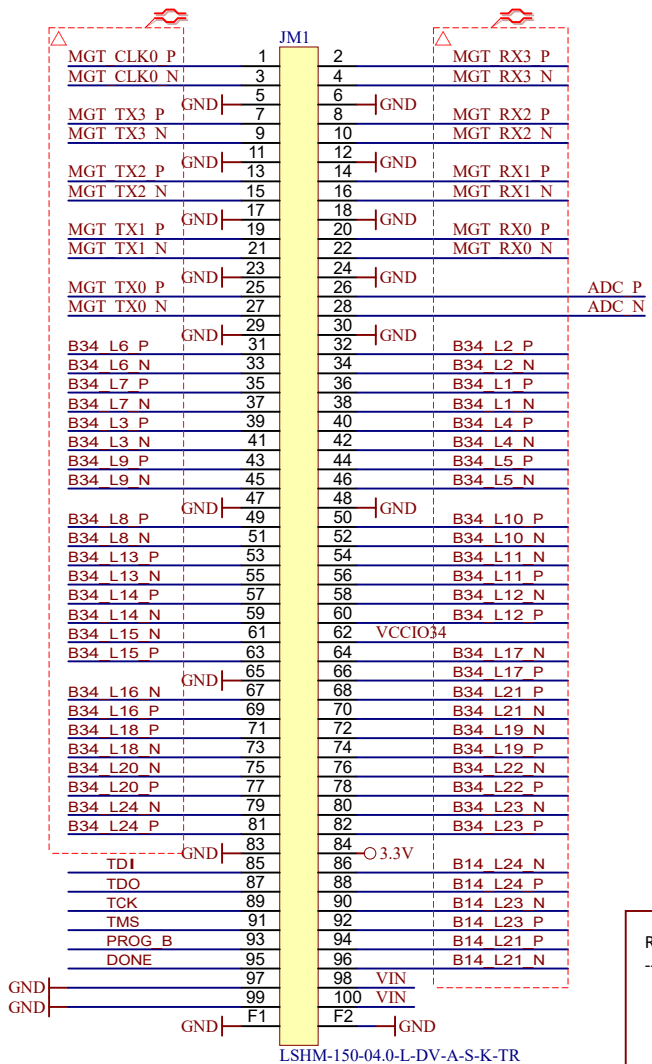



LOGO1  
**TE Logo PRINT Layer**  
 LOGO PRINT

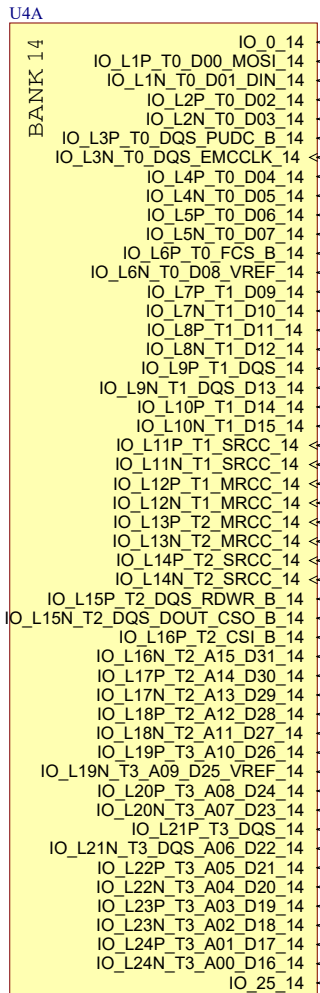


Assembly variant	35-2I
Created by	
Modified by	
Modified at	
SVN Revision	8634

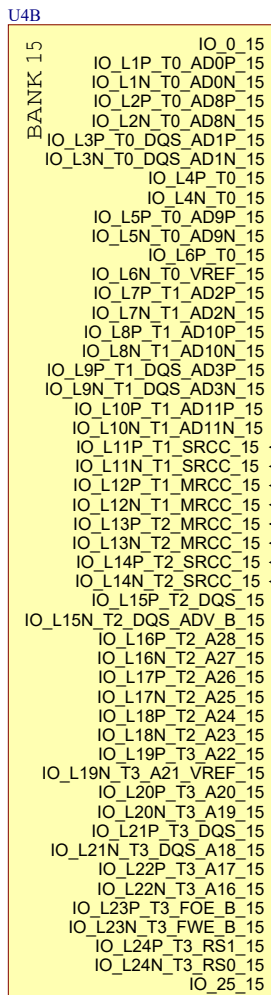
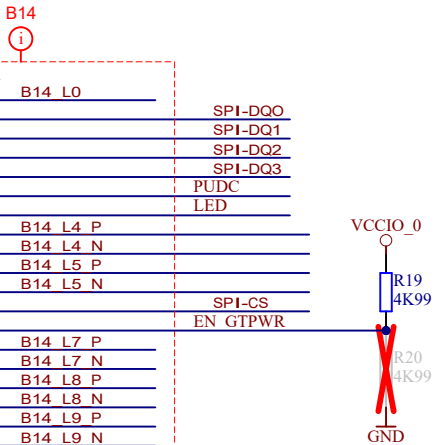
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Date: 2019-02-14	Copyright: Trenz Electronic GmbH / TT	Page1 of 7
Filename: <b>TE0714.SchDoc</b>		

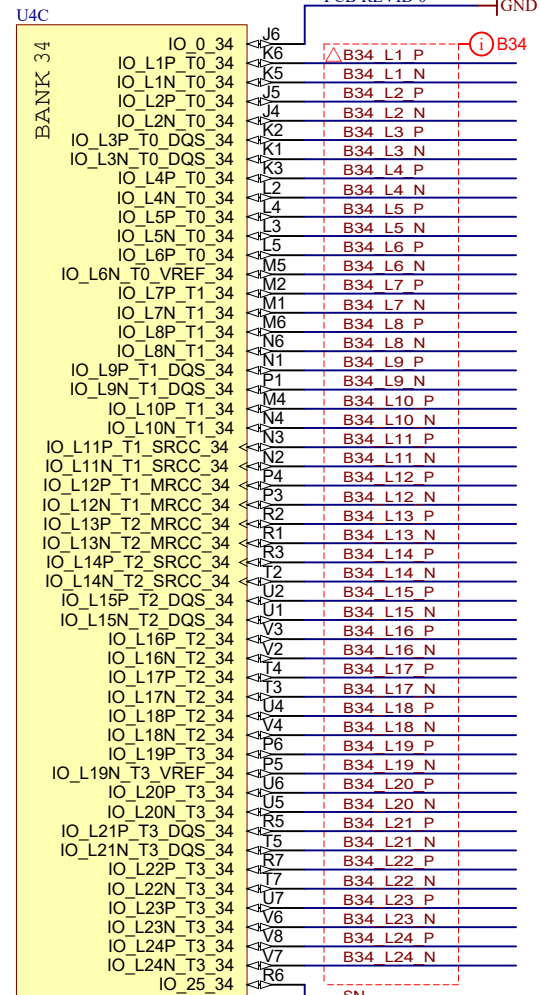
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Date: 2019-02-14	Copyright: Trenz Electronic GmbH / TT	Page2 of 7
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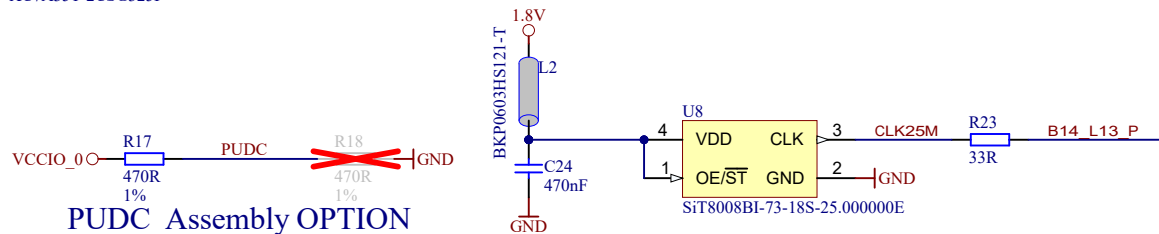
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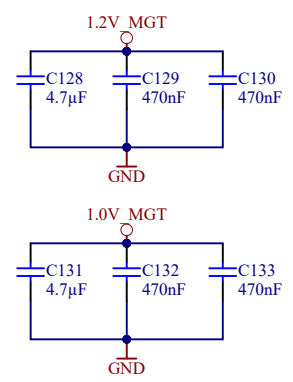
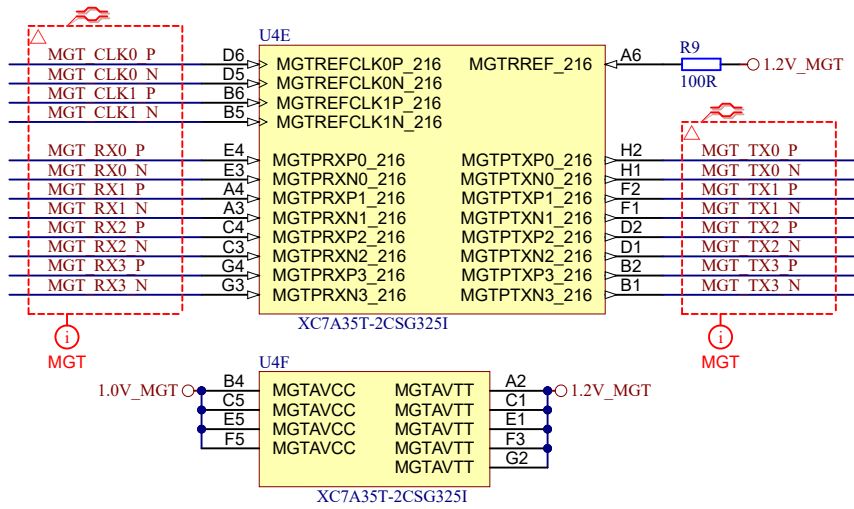
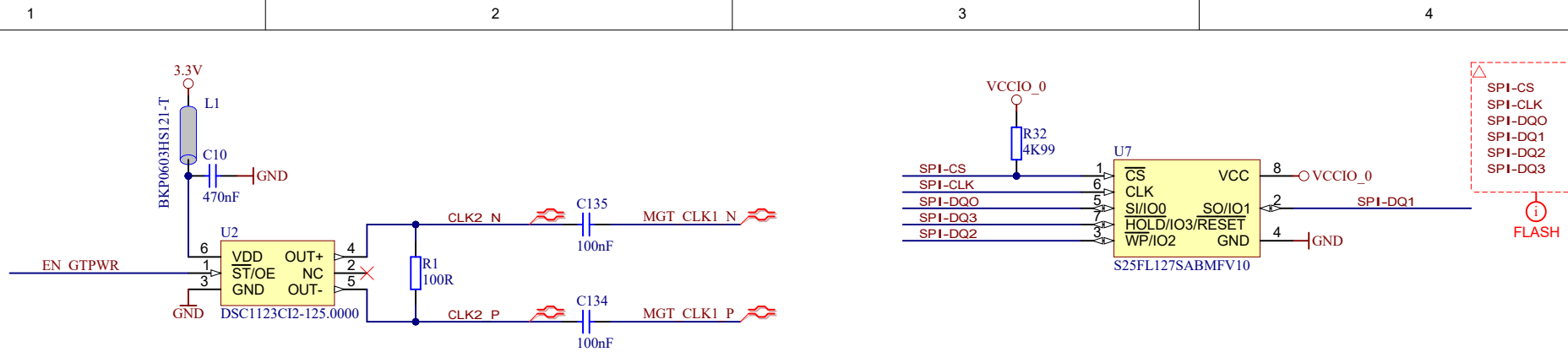

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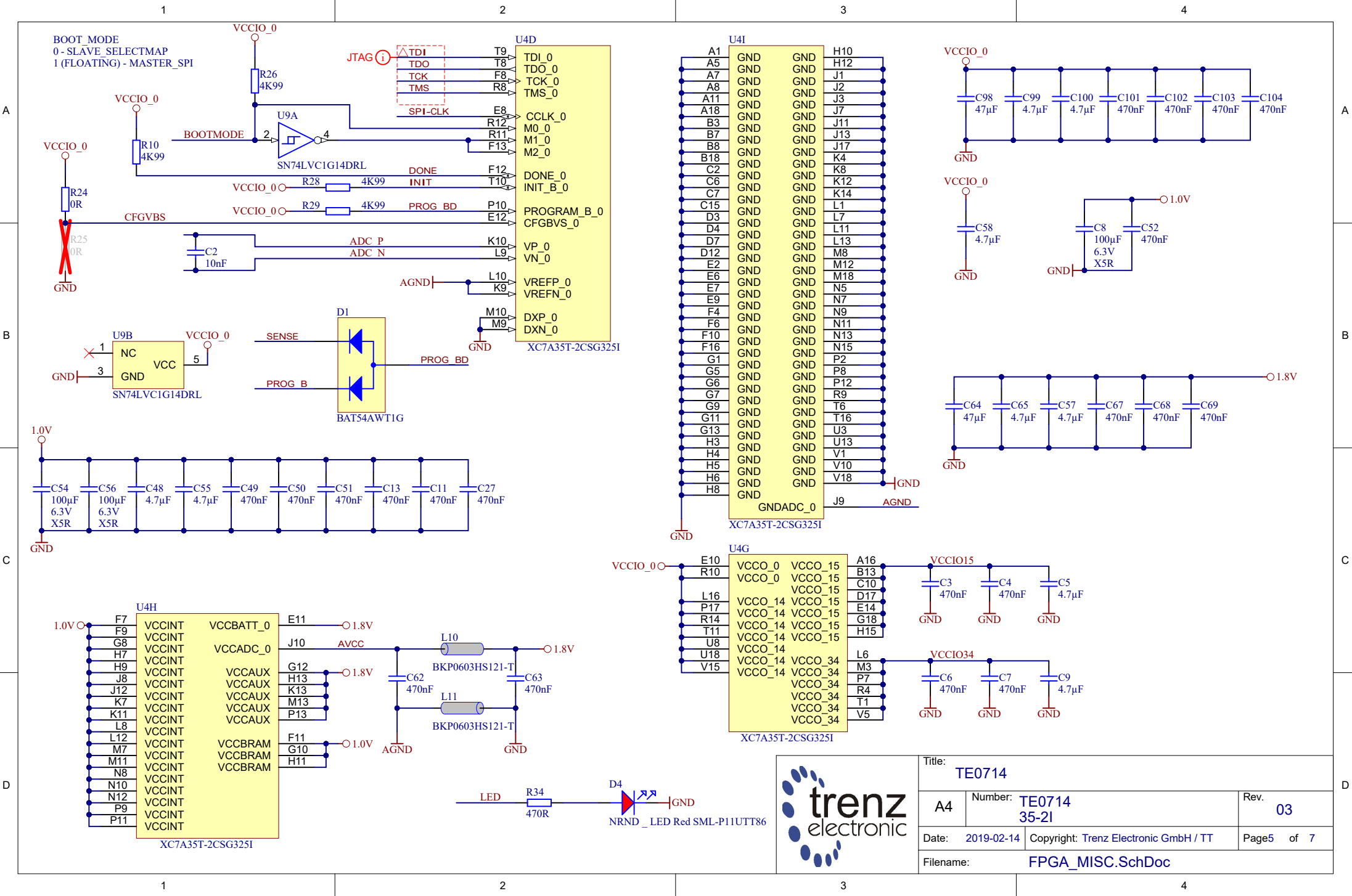
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Title: <b>TE0714</b>			
A4	Number: <b>TE0714 35-21</b>	Rev. <b>03</b>	
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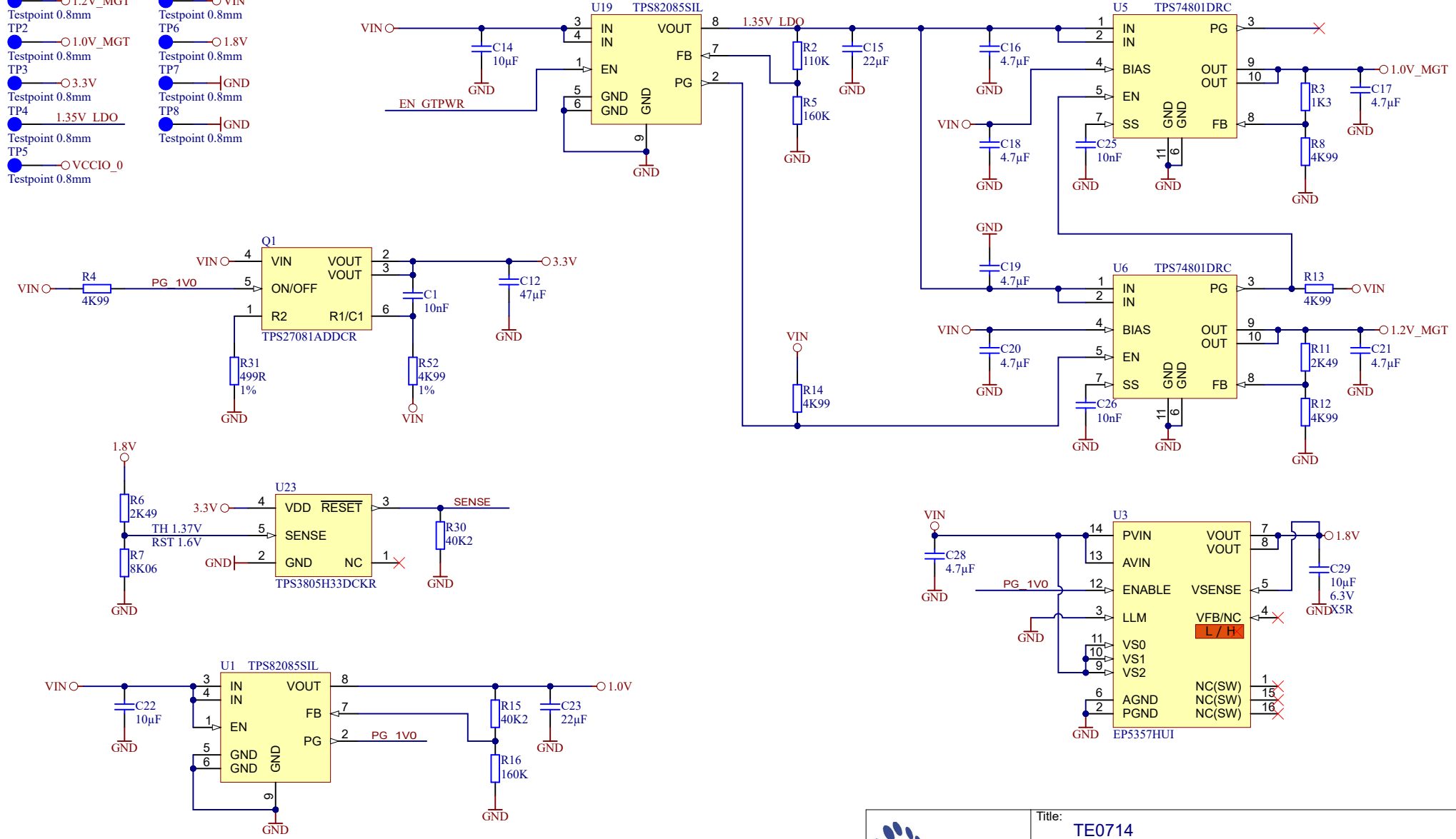



Title: TE0714		
A4	Number: TE0714 35-2I	Rev. 03
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Filename: FPGA_MGT.SchDoc		



Title: TE0714		
A4	Number: TE0714 35-21	Rev. 03
Date: 2019-02-14	Copyright: Trenz Electronic GmbH / TT	Page5 of 7
Filename: FPGA_MISC.SchDoc		

- TP1 ● ○ 1.2V\_MGT  
Testpoint 0.8mm
- TP2 ● ○ 1.0V\_MGT  
Testpoint 0.8mm
- TP3 ● ○ 3.3V  
Testpoint 0.8mm
- TP4 ● ○ 1.35V\_LDO  
Testpoint 0.8mm
- TP5 ● ○ VCCIO\_0  
Testpoint 0.8mm
- TP9 ● ○ VIN  
Testpoint 0.8mm
- TP6 ● ○ 1.8V  
Testpoint 0.8mm
- TP7 ● ○ GND  
Testpoint 0.8mm
- TP8 ● ○ GND  
Testpoint 0.8mm



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A4	Number: <b>TE0714 35-21</b>	Rev. <b>03</b>
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Filename: <b>POWER.SchDoc</b>		

Changes REV 02:


- 1. Added 0 ohm strap option to supply VCCIO0 on B2B connector
- 2. Added PCB Revision sense support. PCB Revision readout possible from HDL Design
- 3. Updated FPGA pin PROG\_B connection. TPS3805H33 push-pull output RESET\_N not affected on baseboard circuit, connected to PROG\_B.
- 4. C8, C54, C56 updated to 100uF for variant 50-2I
- 5. Added testpoints

Changes REV 02A (12.2018):

- 1. New FLASH memory U7 S25FL127SABMFV10

Changes REV 03:

- 1) Changed obsolete component U3 (LXDC2HL18A-052 -> EP5357HUI)
- 2) DXP/DXN connected to GND (recommendation UG475, p31)
- 3) Added serial number to silk
- 4) Changed obsolete component Q1 (TPS27082LDDCR ->TPS27081ADDCR )
- 5) Full update LIB
- 6) Optimized testpoints placement

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	Filename: <b>Revision Changes.SchDoc</b>		